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New Advanced IC Packaging

Battlefield -- Cadence

Design Systems *Evolution of*

semiconductor packaging What

Is Microsystems Packaging

Automotive Semiconductor

Packaging – Trends,

Challenges and Solutions

Semiconductor Package

Overall: Structure, Process

30 years of IC packaging

Packaging of semiconductor

ICs in an iPhone : part 1

Semiconductor Fabrication

Basics - Thin Film

Processes, Doping,

Photolithography, etc. Video

1: Semiconductor Packaging 1

- Wafer Mounting Process

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Custom IC Assembly From Sand
to Silicon: the Making of a
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~~made Transistors, How do~~
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(removing epoxy packaging
from chips to expose the
dies) What's inside a

microchip ? *2.5D ICs or*
interposer technology *Making*
Memory Chips – Process Steps

A simple guide to electronic
components. ~~How Package~~

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Electronic Packaging Video

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system and product level.

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book is assumed to mean
those designs and

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Semiconductor Packaging (Pt.
1) by Rao Tummala
(1997-01-31) by Alan G.
Klopfenstein (Auth Rao
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